



Flexible circuit board materials

フレキシブル基板材料

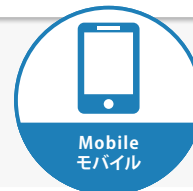
FELIOS

Double-sided copper clad **R-F775**
Single-sided copper clad **R-F770**

Applications 用途

Consumer mobile products (Smartphone, tablet PC),
Medical, Industrial, Avionics, Etc.

モバイル機器 (スマートフォン、タブレット PC)、医療機器、産業機器、航空機器など



Felios adhesiveless flex materials are available in a wide-range of film and copper foil thicknesses to support all applications. Felios offers superior thermal resistance, dimensional stability and quality.

多彩な厚みのラインアップにより、モバイル機器を始め様々な用途に適用可能。また耐熱性や寸法安定性、品質にも優れる。

Superior Thermal Resistance

Wide Product Selection

High dimensional stability

Line-up ラインアップ

Available in various film and copper foil combinations. 様々なフィルム・銅箔の組合せに対応

Copper Foil Thickness		Film Thickness															Unit: mils (mm)
		Sheet Type Max 610mm(MD) x 510mm(TD)								Roll Type W=250mm, 500mm							
		0.5 (0.013)	0.8 (0.02)	1.0 (0.025)	2.0 (0.05)	3.0 (0.075)	4.0 (0.10)	5.0 (0.125)	6.0 (0.15)	0.5 (0.013)	0.8 (0.02)	1.0 (0.025)	2.0 (0.05)	3.0 (0.075)	4.0 (0.10)	5.0 (0.125)	6.0 (0.15)
RA Copper Foil 両面銅箔	1/4oz (9 μm)	●*1	●*1	●*1	●*1	-	-	-	-	●*1	●*1	●*1	●*1	-	-	-	-
	1/3oz (12 μm)	●	●	●	●	●	●	-	-	●	●*1	●	●	●	-	-	-
	1/2oz (18 μm)	●	●	●	●	●	●	●	●	●	●*1	●*2	●*2	●*2	●*1	●*1	-
	1oz (35 μm)	●	●	●	●	●	●	●	●	●*1	●*1	●*2	●*2	●*1	●*1	●*1	-
	2oz (70 μm)	-	●	●	●	●	●	●	●	-	●*1	●*2	●*2	-	-	-	-
ED Copper Foil 片面銅箔	- (2 μm)	●	●	●	●	●	-	-	-	●*1	●*1	●	●	●*1	-	-	-
	1/6oz (6 μm)	●	-	●	●	-	-	-	-	●*1	-	●	●	-	-	-	-
	1/4oz (9 μm)	●	●	●	●	●	●	●	●	●*1	●*1	●	●	●*1	●*1	●*1	-
	1/3oz (12 μm)	●	●	●	●	●	●	●	●	●*1	●*1	●	●	●	●*1	●*1	-
	1/2oz (18 μm)	●	●	●	●	●	●	-	-	●*1	●*1	●	●	●*1	●*1	-	-
	1oz (35 μm)	-	●	●	●	●	●	-	-	-	-	●	●	-	-	-	-

*1 Special option *2 W=610mm is optional.

General properties 一般特性

Item	Test method	Condition	Unit	FELIOS R-F775	
Solder heat resistance	JIS C 6471	A	°C	>330	
		C-96/40/90		260	
Tensile modulus	ASTM D882	A	GPa	7.1	
Tensile strength	Internal method	A	MPa	542	
Peel strength	RA: 1/3oz(12 μm)	JIS C 6471	A	N/mm	1.35
CTE	MD/TD Z-axis	JIS R 3251	50~200°C	ppm/°C	17/19
				ppm/°C	101
Thermal conductivity	Laser flash	A	W/m·K	0.16	
Dimensional stability	IPC-TM-650	After etching MD direction	%	0.00±0.10	
		After etching TD direction		0.00±0.10	
Flammability	UL	A + E-168/70	-	94V-0	

The sample thickness is film 25 μm, copper foil 12 μm.

Our Halogen-free materials are based on JPCA-ES-01-2003 standard and others. 当社ハロゲンフリー材料は、JPCA-ES-01-2003などの定義によるものです。The above data are typical values and not guaranteed values. 上記データは当社測定による代表値であり、保証値ではありません。

Please see the page for "Notes before you use" 商品のご採用に当たっての注意事項はこちら